

| Data Sheet | January 2002 |  |
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|            |              |  |

# 75A, 1200V Hyperfast Diode

The RHRG75120 is a hyperfast diode with soft recovery characteristics ( $t_{rr}$  < 85ns). It has half the recovery time of ultrafast diodes and is silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of high frequency switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery characteristic minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

Formerly developmental type TA49042.

# Ordering Information

| PART NUMBER | PACKAGE | BRAND     |
|-------------|---------|-----------|
| RHRG75120   | TO-247  | RHRG75120 |

NOTE: When ordering, use the entire part number.

# Symbol



### **Features**

| • | Hyperfast with Soft Recovery | <85ns             |
|---|------------------------------|-------------------|
| • | Operating Temperature1       | 75 <sup>0</sup> C |
| • | Reverse Voltage              | 200V              |

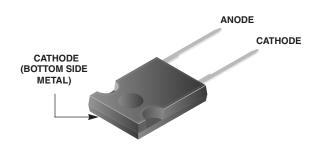
- · Avalanche Energy Rated
- Planar Construction

# **Applications**

- · Switching Power Supplies
- · Power Switching Circuits
- · General Purpose

### **Packaging**

**JEDEC STYLE TO-247** 



#### **Absolute Maximum Ratings** $T_C = 25^{\circ}C$ RHRG75120 **UNITS** 1200 1200 DC Blocking Voltage ......V<sub>B</sub> 1200 75 Α $(T_C = 42^{\circ}C)$ 150 Α (Square Wave, 20kHz) Nonrepetitive Peak Surge Current IFSM 500 Α (Halfwave, 1 Phase, 60Hz) 190 W Avalanche Energy (See Figures 7 and 8) ...... EAVL 50 mJ -65 to 175 $^{\circ}C$

**Electrical Specifications**  $T_C = 25^{\circ}C$ , Unless Otherwise Specified

| SYMBOL          | TEST CONDITION                                 | MIN | TYP | MAX | UNITS |
|-----------------|--|-----|-----|-----|-------|
| V <sub>F</sub>  | I <sub>F</sub> = 75A                           | -   | -   | 3.2 | V     |
|                 | I <sub>F</sub> = 75A, T <sub>C</sub> = 150°C   | -   | -   | 2.6 | V     |
| I <sub>R</sub>  | V <sub>R</sub> = 1200V                         | -   | -   | 250 | μΑ    |
|                 | V <sub>R</sub> = 1200V, T <sub>C</sub> = 150°C | -   | -   | 2   | mA    |
| t <sub>rr</sub> | $I_F = 1A$ , $dI_F/dt = 100A/\mu s$            | -   | -   | 85  | ns    |
|                 | $I_F = 75A$ , $dI_F/dt = 100A/\mu s$           | -   | -   | 100 | ns    |
| t <sub>a</sub>  | $I_F = 75A$ , $dI_F/dt = 100A/\mu s$           | -   | 60  | -   | ns    |
| t <sub>b</sub>  | $I_F = 75A$ , $dI_F/dt = 100A/\mu s$           | -   | 25  | -   | ns    |
| $R_{	heta JC}$  |  | -   | -   | 0.8 | °C/W  |

### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

I<sub>R</sub> = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 6), summation of  $t_a + t_b$ .

 $t_a$  = Time to reach peak reverse current (See Figure 6).

t<sub>b</sub> = Time from peak I<sub>RM</sub> to projected zero crossing of I<sub>RM</sub> based on a straight line from peak I<sub>RM</sub> through 25% of I<sub>RM</sub> (See Figure 6).

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

# **Typical Performance Curves**

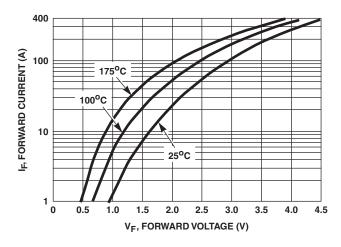


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

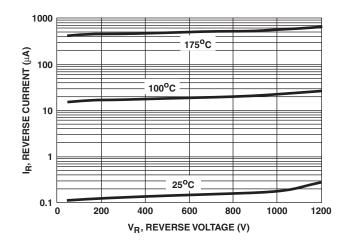


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

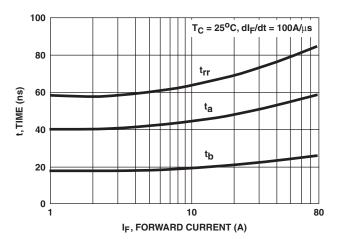


FIGURE 3. t<sub>rr</sub>, t<sub>a</sub> AND t<sub>b</sub> CURVES vs FORWARD CURRENT

# 80 60 DC SQ. WAVE 20 25 50 75 100 125 150 175 T<sub>C</sub>, CASE TEMPERATURE (°C)

FIGURE 4. CURRENT DERATING CURVE

### Test Circuits and Waveforms

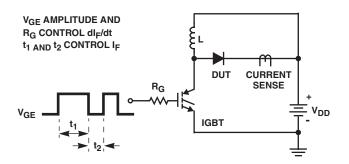


FIGURE 5.  $t_{rr}$  TEST CIRCUIT

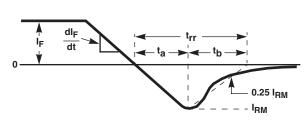


FIGURE 6. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

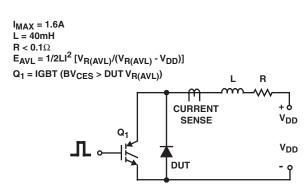


FIGURE 7. AVALANCHE ENERGY TEST CIRCUIT

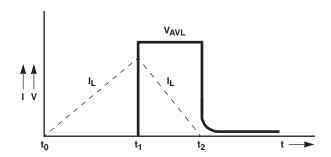


FIGURE 8. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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|--------------------------|---------------------------|---|
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